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(54) **Method for packaging an organic light emitting display with a frit seal and a reinforcing structure**

Verfahren zur Verpackung einer organischen lichtemittierenden Anzeige mit Frittendichtung und Verstärkungsstruktur

Procédé d'emballage de panneau d'affichage électroluminescent organique avec soudure au verre fritté et structure renforcée

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## Description

### Field of the Invention

[0001] The present invention relates to organic light emitting display devices, and more particularly for packaging of the device.

### Discussion of Related Art

[0002] In recent years, organic light emitting displays have been widely used and are relatively simple. The organic light emitting display is referred to as an organic light emitting device, and is an emissive device using an organic layer as an emission layer. Since the organic light emitting display can eliminate need for a back light as required in a liquid crystal display, it can be made thin and light weight. Thus, the organic light emitting display has been actively developed as a display panel in a portable information terminal such as mobile computer, portable telephone, portable game device, and electronic book.

[0003] In general, the organic light emitting display has a structure in which at least one organic layer having an emission layer is interposed between a pair of electrodes, namely, a first electrode and a second electrode. The first electrode is formed on a substrate, and functions as an anode to inject holes. An organic layer is formed at an upper portion of the first electrode. The second electrode is formed on the organic layer to face the first electrode, and functions as a cathode to inject electrons.

[0004] When moisture or oxygen from ambient environment is introduced in a device, the life of such an organic light emitting display is reduced, emission efficiency is deteriorated, and emission color changes due to oxidation and peeling.

[0005] Therefore, in manufacturing the organic light emitting display, it is well known that the device is separate and sealed from an outside to prevent moisture from infiltrating into it. In the sealing method, after organic macromolecule such as polyester (PET) is laminated at an upper portion of the organic light emitting display, or a cover or a cap is formed by a glass or a metal having absorbent, the inside thereof is filled with nitrogen gas. Then, edges of the cover or the cap are capsule-sealed by a sealant such as epoxy.

In US 2004/0069017 a display element is described. The display element comprises a glass substrate, on which a luminescent body is arranged, a glass cap and a sealing layer of frit placed between the rim of the glass substrate and the rim of the glass cap.

[0006] However, it is impossible for the conventional method to prevent the introduction of device destructive factors such as moisture or oxygen from an outside by 100 %. Consequently, a structure of the device is disadvantageous to be applied to an active surface emitting type organic light emitting display weak to moisture, and a process to embody such a method is complicated. In

order to solve the aforementioned problems, a capsule sealing method is devised to enhance an adhesion between a device substrate and a cap using a frit as a sealant. U.S. Patent No. 6,998,776 B2 discloses a structure of sealing an organic light emitting display by coating a frit at a glass substrate.

### SUMMARY OF CERTAIN INVENTIVE ASPECTS

[0007] An aspect of the invention provides a method for making an organic light emitting display device, which may comprise: providing first and second devices, each device comprising: a first substrate comprising front and back surfaces and a first side surface, a second substrate comprising front and back surfaces and a first side surface opposing the first substrate, an array of organic light emitting pixels interposed between the first and second substrates, a frit seal interposed between the first substrate and the second substrate while surrounding the array, wherein the frit seal, the first substrate and the second substrate together define an enclosed space in which the array is located, the frit seal comprising a first side surface, and a first side comprising the first side surfaces of the first substrate, the second substrate and the frit seal; arranging the first and second devices such that the first substrate of the first device opposes the first or second substrate of the second device and that the first sides of the first and second devices face substantially the same direction; applying a material onto the first sides of the first and second devices, the material being configured to form a reinforcing structure when cured; and curing the material so as to form a reinforcing structure comprising a first portion contacting the first side of the first device and a second portion contacting the first side of the second device.

[0008] In the foregoing method, arranging may comprise providing a holder configured to hold the first and second devices, and holding the first and second devices such that the first substrate of the first device opposing the first or second substrate of the second device and that the first sides of the first and second devices face substantially the same direction. Applying the material may comprise causing a medium retaining the material to contact the first sides of the first and second devices. Applying may comprise sliding the medium on the first sides of the first and second devices. The material may be applied while holding the first and second devices together. The medium may comprise a brush. The medium may be arranged with a roll comprising a rotatable cylinder, and wherein applying may comprise rolling the roll over the first sides of the first and second devices while contacting at least part of the first sides.

[0009] Still in the foregoing method, the first substrate, the second substrate and the frit seal in combination may form a gap space outside the enclosed space in each of the first and second devices, and wherein at least part of the material may enter into the gap space. Applying the material may comprise causing the material to enter

into the gap space. At least part of the material entering into the gap space may spontaneously move toward the frit seal. The gap space may have a depth from the first side surface of the first substrate to the first side surface of the frit seal, and wherein the depth may be from about 0.3 mm to about 0.7 mm. The distance between the first and second substrates in the gap space may be from about 2  $\mu\text{m}$  to about 30  $\mu\text{m}$ .

**[0010]** In the foregoing method, applying the material may comprise causing the material to contact at least part of the first side of the first device and at least part of the first side of the second device. Applying the material may comprise causing the material to contact the first side surface of the frit seal in each of the first and second device. The material may have a viscosity less than about 200 cp. Arranging may comprise placing an insert between the first substrate of the first device and the first or second substrate of the second device. Arranging may comprise contacting the first substrate of the first device with the first or second substrate of the second device.

**[0011]** Still in the foregoing method, the first substrate of the first device is arranged substantially parallel to the first or second substrate of the second device. The first side surface of the frit seal may be substantially parallel to the first side surface of the first substrate. The first portion may contact the frit seal of the first device. The first portion may contact at least one of the first and second substrates. The first and second portions are integrated after curing. The method may further comprise separating the first portion from the second portion. Each of the first and second devices comprises a second side comprising second side surfaces of the first substrate, the second substrate and the frit seal, wherein the method may further comprise applying the material with the second sides of the first and second devices. The medium may move in a direction when applying the material, and wherein an angle between one of the substrates of the first and second devices and the direction of the movement may be about 5 to 90 degrees when forming the mass of the material. The medium may move in a direction when applying the material, and wherein an angle between one of the substrates of the first and second devices and the direction of the movement may be about 10 to about 89 degrees when forming the mass of the material.

**[0012]** The foregoing method may further comprising providing at least one additional device comprising a first substrate comprising front and back surfaces and a first side surface, a second substrate comprising front and back surfaces and a first side surface and opposing the first substrate, an array of organic light emitting pixels interposed between the first and second substrates, a frit seal interposed between the first substrate and the second substrate while surrounding the array, wherein the frit seal, the first substrate and the second substrate may together define an enclosed space in which the array is located, the frit seal comprising a first side surface, and a first side comprising the first side surfaces of the first

substrate, the second substrates and the frit seal, wherein arranging may further arrange the at least one additional device together with the first and second devices, wherein applying may further apply the material on the at least one additional device, and wherein curing may form at least one additional structure, each of which contacts the first side of each of the at least one additional device. The frit seal may comprise one or more materials selected from the group consisting of magnesium oxide (MgO), calcium oxide (CaO), barium oxide (BaO), lithium oxide ( $\text{Li}_2\text{O}$ ), sodium oxide ( $\text{Na}_2\text{O}$ ), potassium oxide ( $\text{K}_2\text{O}$ ), boron oxide ( $\text{B}_2\text{O}_3$ ), vanadium oxide ( $\text{V}_2\text{O}_5$ ), zinc oxide (ZnO), tellurium oxide ( $\text{TeO}_2$ ), aluminum oxide ( $\text{Al}_2\text{O}_3$ ), silicon dioxide ( $\text{SiO}_2$ ), lead oxide (PbO), tin oxide (SnO), phosphorous oxide ( $\text{P}_2\text{O}_5$ ), ruthenium oxide ( $\text{Ru}_2\text{O}$ ), rubidium oxide ( $\text{Rb}_2\text{O}$ ), rhodium oxide ( $\text{Rh}_2\text{O}$ ), ferrite oxide ( $\text{Fe}_2\text{O}_3$ ), copper oxide (CuO), titanium oxide ( $\text{TiO}_2$ ), tungsten oxide ( $\text{WO}_3$ ), bismuth oxide ( $\text{Bi}_2\text{O}_3$ ), antimony oxide ( $\text{Sb}_2\text{O}_3$ ), lead-borate glass, tin-phosphate glass, vanadate glass, and borosilicate.

**[0013]** Another aspect of the present invention provides a method for manufacturing an organic light emitting display, which fill a reinforcing member at once in a liquid phase between a first substrate and a second substrate by dipping non-pixel regions of unit display panels in the reinforcing member.

**[0014]** Still another aspect of the present invention provides a method for manufacturing an organic light emitting display, comprising the steps of: (i) forming an organic light emitting device at a plurality of pixel regions of a first mother substrate, the first mother substrate including the plurality of pixel regions and a plurality of non-pixel regions; (ii) forming a frit at a second mother substrate corresponding to the non-pixel regions of the first mother substrate; (iii) coalescing the second mother substrate to the first mother substrate so that the plurality of pixel regions of the first mother substrate are sealed by the frit; (iv) cutting the first and second mother substrates coalesced to separate the first and second mother substrates from unit display panels; (v) aligning the unit display panels; and (vi) coating a reinforcing member at an outer side surface of each of the unit display panels. The reinforcing member is formed by a roll printing method. Preferably, the method further comprises a step of curing the reinforcing member after coating the reinforcing member. The reinforcing member is cured by ultraviolet ray, natural curing, or thermal process.

## BRIEF DESCRIPTION OF THE DRAWINGS

**[0015]** These and other aspects and advantages of the invention will become apparent and more readily appreciated from the following description of the embodiments, taken in conjunction with the accompanying drawings of which:

**[0016]** FIG. 1a to FIG. 1f are cross-sectional views showing a method for manufacturing an organic light emitting display according to an embodiment of the

present invention;

**[0017]** FIG. 2a to FIG. 2f are perspective views showing a method for manufacturing an organic light emitting display according to an embodiment of the present invention;

**[0018]** FIG. 3A is a schematic exploded view of a passive matrix type organic light emitting display device in accordance with one embodiment;

**[0019]** FIG. 3B is a schematic exploded view of an active matrix type organic light emitting display device in accordance with one embodiment;

**[0020]** FIG. 3C is a schematic top plan view of an organic light emitting display in accordance with one embodiment;

**[0021]** FIG. 3D is a cross-sectional view of the organic light emitting display of FIG. 3C, taken along the line d-d; and

**[0022]** FIG. 3E is a schematic perspective view illustrating mass production of organic light emitting devices in accordance with one embodiment.

## DETAILED DESCRIPTION OF EMBODIMENTS

**[0023]** Hereinafter, embodiments according to the present invention will be described with reference to the accompanying drawings.

**[0024]** An organic light emitting display (OLED) is a display device comprising an array of organic light emitting diodes. Organic light emitting diodes are solid state devices which include an organic material and are adapted to generate and emit light when appropriate electrical potentials are applied.

**[0025]** OLEDs can be generally grouped into two basic types dependent on the arrangement with which the stimulating electrical current is provided. Fig. 3A schematically illustrates an exploded view of a simplified structure of a passive matrix type OLED 1000. Fig. 3B schematically illustrates a simplified structure of an active matrix type OLED 1001. In both configurations, the OLED 1000, 1001 includes OLED pixels built over a substrate 1002, and the OLED pixels include an anode 1004, a cathode 1006 and an organic layer 1010. When an appropriate electrical current is applied to the anode 1004, electric current flows through the pixels and visible light is emitted from the organic layer.

**[0026]** Referring to Fig. 3A, the passive matrix OLED (PMOLED) design includes elongate strips of anode 1004 arranged generally perpendicular to elongate strips of cathode 1006 with organic layers interposed therebetween. The intersections of the strips of cathode 1006 and anode 1004 define individual OLED pixels where light is generated and emitted upon appropriate excitation of the corresponding strips of anode 1004 and cathode 1006. PMOLEDs provide the advantage of relatively simple fabrication.

**[0027]** Referring to Fig. 3B, the active matrix OLED (AMOLED) includes local driving circuits 1012 arranged between the substrate 1002 and an array of OLED pixels.

An individual pixel of AMOLEDs is defined between the common cathode 1006 and an anode 1004, which is electrically isolated from other anodes. Each driving circuit 1012 is coupled with an anode 1004 of the OLED pixels and further coupled with a data line 1016 and a scan line 1018. In embodiments, the scan lines 1018 supply scan signals that select rows of the driving circuits, and the data lines 1016 supply data signals for particular driving circuits. The data signals and scan signals stimulate the local driving circuits 1012, which excite the anodes 1004 so as to emit light from their corresponding pixels.

**[0028]** In the illustrated AMOLED, the local driving circuits 1012, the data lines 1016 and scan lines 1018 are buried in a planarization layer 1014, which is interposed between the pixel array and the substrate 1002. The planarization layer 1014 provides a planar top surface on which the organic light emitting pixel array is formed. The planarization layer 1014 may be formed of organic or inorganic materials, and formed of two or more layers although shown as a single layer. The local driving circuits 1012 are typically formed with thin film transistors (TFT) and arranged in a grid or array under the OLED pixel array. The local driving circuits 1012 may be at least partly made of organic materials, including organic TFT. AMOLEDs have the advantage of fast response time improving their desirability for use in displaying data signals. Also, AMOLEDs have the advantages of consuming less power than passive matrix OLEDs.

**[0029]** Referring to common features of the PMOLED and AMOLED designs, the substrate 1002 provides structural support for the OLED pixels and circuits. In various embodiments, the substrate 1002 can comprise rigid or flexible materials as well as opaque or transparent materials, such as plastic, glass, and/or foil. As noted above, each OLED pixel or diode is formed with the anode 1004, cathode 1006 and organic layer 1010 interposed therebetween. When an appropriate electrical current is applied to the anode 1004, the cathode 1006 injects electrons and the anode 1004 injects holes. In certain embodiments, the anode 1004 and cathode 1006 are inverted; i.e., the cathode is formed on the substrate 1002 and the anode is oppositely arranged.

**[0030]** Interposed between the cathode 1006 and anode 1004 are one or more organic layers. More specifically, at least one emissive or light emitting layer is interposed between the cathode 1006 and anode 1004. The light emitting layer may comprise one or more light emitting organic compounds. Typically, the light emitting layer is configured to emit visible light in a single color such as blue, green, red or white. In the illustrated embodiment, one organic layer 1010 is formed between the cathode 1006 and anode 1004 and acts as a light emitting layer. Additional layers, which can be formed between the anode 1004 and cathode 1006, can include a hole transporting layer, a hole injection layer, an electron transporting layer and an electron injection layer.

**[0031]** Hole transporting and/or injection layers can be interposed between the light emitting layer 1010 and the

anode 1004. Electron transporting and/or injecting layers can be interposed between the cathode 1006 and the light emitting layer 1010. The electron injection layer facilitates injection of electrons from the cathode 1006 toward the light emitting layer 1010 by reducing the work function for injecting electrons from the cathode 1006. Similarly, the hole injection layer facilitates injection of holes from the anode 1004 toward the light emitting layer 1010. The hole and electron transporting layers facilitate movement of the carriers injected from the respective electrodes toward the light emitting layer.

**[0032]** In some embodiments, a single layer may serve both electron injection and transportation functions or both hole injection and transportation functions. In some embodiments, one or more of these layers are lacking. In some embodiments, one or more organic layers are doped with one or more materials that help injection and/or transportation of the carriers. In embodiments where only one organic layer is formed between the cathode and anode, the organic layer may include not only an organic light emitting compound but also certain functional materials that help injection or transportation of carriers within that layer.

**[0033]** There are numerous organic materials that have been developed for use in these layers including the light emitting layer. Also, numerous other organic materials for use in these layers are being developed. In some embodiments, these organic materials may be macromolecules including oligomers and polymers. In some embodiments, the organic materials for these layers may be relatively small molecules. The skilled artisan will be able to select appropriate materials for each of these layers in view of the desired functions of the individual layers and the materials for the neighboring layers in particular designs.

**[0034]** In operation, an electrical circuit provides appropriate potential between the cathode 1006 and anode 1004. This results in an electrical current flowing from the anode 1004 to the cathode 1006 via the interposed organic layer(s). In one embodiment, the cathode 1006 provides electrons to the adjacent organic layer 1010. The anode 1004 injects holes to the organic layer 1010. The holes and electrons recombine in the organic layer 1010 and generate energy particles called "excitons." The excitons transfer their energy to the organic light emitting material in the organic layer 1010, and the energy is used to emit visible light from the organic light emitting material. The spectral characteristics of light generated and emitted by the OLED 1000, 1001 depend on the nature and composition of organic molecules in the organic layer(s). The composition of the one or more organic layers can be selected to suit the needs of a particular application by one of ordinary skill in the art.

**[0035]** OLED devices can also be categorized based on the direction of the light emission. In one type referred to as "top emission" type, OLED devices emit light and display images through the cathode or top electrode 1006. In these embodiments, the cathode 1006 is made

of a material transparent or at least partially transparent with respect to visible light. In certain embodiments, to avoid losing any light that can pass through the anode or bottom electrode 1004, the anode may be made of a material substantially reflective of the visible light. A second type of OLED devices emits light through the anode or bottom electrode 1004 and is called "bottom emission" type. In the bottom emission type OLED devices, the anode 1004 is made of a material which is at least partially transparent with respect to visible light. Often, in bottom emission type OLED devices, the cathode 1006 is made of a material substantially reflective of the visible light. A third type of OLED devices emits light in two directions, e.g. through both anode 1004 and cathode 1006. Depending upon the direction(s) of the light emission, the substrate may be formed of a material which is transparent, opaque or reflective of visible light.

**[0036]** In many embodiments, an OLED pixel array 1021 comprising a plurality of organic light emitting pixels is arranged over a substrate 1002 as shown in Fig. 3C. In embodiments, the pixels in the array 1021 are controlled to be turned on and off by a driving circuit (not shown), and the plurality of the pixels as a whole displays information or image on the array 1021. In certain embodiments, the OLED pixel array 1021 is arranged with respect to other components, such as drive and control electronics to define a display region and a non-display region. In these embodiments, the display region refers to the area of the substrate 1002 where OLED pixel array 1021 is formed. The non-display region refers to the remaining areas of the substrate 1002. In embodiments, the non-display region can contain logic and/or power supply circuitry. It will be understood that there will be at least portions of control/drive circuit elements arranged within the display region. For example, in PMOLEDs, conductive components will extend into the display region to provide appropriate potential to the anode and cathodes. In AMOLEDs, local driving circuits and data/scan lines coupled with the driving circuits will extend into the display region to drive and control the individual pixels of the AMOLEDs.

**[0037]** One design and fabrication consideration in OLED devices is that certain organic material layers of OLED devices can suffer damage or accelerated deterioration from exposure to water, oxygen or other harmful gases. Accordingly, it is generally understood that OLED devices be sealed or encapsulated to inhibit exposure to moisture and oxygen or other harmful gases found in a manufacturing or operational environment. Fig. 3D schematically illustrates a cross-section of an encapsulated OLED device 1011 having a layout of Fig. 3C and taken along the line d-d of Fig. 3C. In this embodiment, a generally planar top plate or substrate 1061 engages with a seal 1071 which further engages with a bottom plate or substrate 1002 to enclose or encapsulate the OLED pixel array 1021. In other embodiments, one or more layers are formed on the top plate 1061 or bottom plate 1002, and the seal 1071 is coupled with the bottom or top sub-

strate 1002, 1061 via such a layer. In the illustrated embodiment, the seal 1071 extends along the periphery of the OLED pixel array 1021 or the bottom or top plate 1002, 1061.

**[0038]** In embodiments, the seal 1071 is made of a frit material as will be further discussed below. In various embodiments, the top and bottom plates 1061, 1002 comprise materials such as plastics, glass and/or metal foils which can provide a barrier to passage of oxygen and/or water to thereby protect the OLED pixel array 1021 from exposure to these substances. In embodiments, at least one of the top plate 1061 and the bottom plate 1002 are formed of a substantially transparent material.

**[0039]** To lengthen the life time of OLED devices 1011, it is generally desired that seal 1071 and the top and bottom plates 1061, 1002 provide a substantially non-permeable seal to oxygen and water vapor and provide a substantially hermetically enclosed space 1081. In certain applications, it is indicated that the seal 1071 of a frit material in combination with the top and bottom plates 1061, 1002 provide a barrier to oxygen of less than approximately  $10^{-3}$  cc(m<sup>2</sup>-day) and to water of less than  $10^{-6}$  g(m<sup>2</sup>-day). Given that some oxygen and moisture can permeate into the enclosed space 1081, in some embodiments, a material that can take up oxygen and/or moisture is formed within the enclosed space 1081.

**[0040]** The seal 1071 has a width W, which is its thickness in a direction parallel to a surface of the top or bottom substrate 1061, 1002 as shown in Fig. 3D. The width varies among embodiments and ranges from about 300  $\mu$ m to about 3000  $\mu$ m, optionally from about 500  $\mu$ m to about 1500  $\mu$ m. Also, the width may vary at different positions of the seal 1071. In some embodiments, the width of the seal 1071 may be the largest where the seal 1071 contacts one of the bottom and top substrate 1002, 1061 or a layer formed thereon. The width may be the smallest where the seal 1071 contacts the other. The width variation in a single cross-section of the seal 1071 relates to the cross-sectional shape of the seal 1071 and other design parameters.

**[0041]** The seal 1071 has a height H, which is its thickness in a direction perpendicular to a surface of the top or bottom substrate 1061, 1002 as shown in Fig. 3D. The height varies among embodiments and ranges from about 2  $\mu$ m to about 30  $\mu$ m, optionally from about 10  $\mu$ m to about 15  $\mu$ m. Generally, the height does not significantly vary at different positions of the seal 1071. However, in certain embodiments, the height of the seal 1071 may vary at different positions thereof.

**[0042]** In the illustrated embodiment, the seal 1071 has a generally rectangular cross-section. In other embodiments, however, the seal 1071 can have other various cross-sectional shapes such as a generally square cross-section, a generally trapezoidal cross-section, a cross-section with one or more rounded edges, or other configuration as indicated by the needs of a given application. To improve hermeticity, it is generally desired to increase the interfacial area where the seal 1071 directly contacts

the bottom or top substrate 1002, 1061 or a layer formed thereon. In some embodiments, the shape of the seal can be designed such that the interfacial area can be increased.

**[0043]** The seal 1071 can be arranged immediately adjacent the OLED array 1021, and in other embodiments, the seal 1071 is spaced some distance from the OLED array 1021. In certain embodiment, the seal 1071 comprises generally linear segments that are connected together to surround the OLED array 1021. Such linear segments of the seal 1071 can extend, in certain embodiments, generally parallel to respective boundaries of the OLED array 1021. In other embodiment, one or more of the linear segments of the seal 1071 are arranged in a non-parallel relationship with respective boundaries of the OLED array 1021. In yet other embodiments, at least part of the seal 1071 extends between the top plate 1061 and bottom plate 1002 in a curvilinear manner.

**[0044]** As noted above, in certain embodiments, the seal 1071 is formed using a frit material or simply "frit" or glass frit," which includes fine glass particles. The frit particles includes one or more of magnesium oxide (MgO), calcium oxide (CaO), barium oxide (BaO), lithium oxide (Li<sub>2</sub>O), sodium oxide (Na<sub>2</sub>O) potassium oxide (K<sub>2</sub>O), boron oxide (B<sub>2</sub>O<sub>3</sub>), vanadium oxide (V<sub>2</sub>O<sub>5</sub>), zinc oxide (ZnO), tellurium oxide (TeO<sub>2</sub>), aluminum oxide (Al<sub>2</sub>O<sub>3</sub>), silicon dioxide (SiO<sub>2</sub>), lead oxide (PbO), tin oxide (SnO), phosphorous oxide (P<sub>2</sub>O<sub>5</sub>), ruthenium oxide (Ru<sub>2</sub>O), rubidium oxide (Rb<sub>2</sub>O), rhodium oxide (Rh<sub>2</sub>O), ferrite oxide (Fe<sub>2</sub>O<sub>3</sub>), copper oxide (CuO), titanium oxide (TiO<sub>2</sub>), tungsten oxide (WO<sub>3</sub>), bismuth oxide (Bi<sub>2</sub>O<sub>3</sub>), antimony oxide (Sb<sub>2</sub>O<sub>3</sub>), lead-borate glass, tin-phosphate glass, vanadate glass, and borosilicate, etc. In embodiments, these particles range in size from about 2  $\mu$ m to about 30  $\mu$ m, optionally about 5  $\mu$ m to about 10  $\mu$ m, although not limited only thereto. The particles can be as large as about the distance between the top and bottom substrates 1061, 1002 or any layers formed on these substrates where the frit seal 1071 contacts.

**[0045]** The frit material used to form the seal 1071 can also include one or more filler or additive materials. The filler or additive materials can be provided to adjust an overall thermal expansion characteristic of the seal 1071 and/or to adjust the absorption characteristics of the seal 1071 for selected frequencies of incident radiant energy. The filler or additive material(s) can also include inversion and/or additive fillers to adjust a coefficient of thermal expansion of the frit. For example, the filler or additive materials can include transition metals, such as chromium (Cr), iron (Fe), manganese (Mn), cobalt (Co), copper (Cu), and/or vanadium. Additional materials for the filler or additives include ZnSiO<sub>4</sub>, PbTiO<sub>3</sub>, ZrO<sub>2</sub>, eucryptite.

**[0046]** In embodiments, a frit material as a dry composition contains glass particles from about 20 to 90 about wt%, and the remaining includes fillers and/or additives. In some embodiments, the frit paste contains about 10-30 wt% organic materials and about 70-90% inorganic materials. In some embodiments, the frit paste contains

about 20 wt% organic materials and about 80 wt% inorganic materials. In some embodiments, the organic materials may include about 0-30 wt% binder(s) and about 70-100 wt% solvent(s). In some embodiments, about 10 wt% is binder(s) and about 90 wt% is solvent(s) among the organic materials. In some embodiments, the inorganic materials may include about 0-10 wt% additives, about 20-40 wt% fillers and about 50-80 wt% glass powder. In some embodiments, about 0-5 wt% is additive(s), about 25-30 wt% is filler(s) and about 65-75 wt% is the glass powder among the inorganic materials.

**[0047]** In forming a frit seal, a liquid material is added to the dry frit material to form a frit paste. Any organic or inorganic solvent with or without additives can be used as the liquid material. In embodiments, the solvent includes one or more organic compounds. For example, applicable organic compounds are ethyl cellulose, nitro cellulose, hydroxyl propyl cellulose, butyl carbitol acetate, terpineol, butyl cellusolve, acrylate compounds. Then, the thus formed frit paste can be applied to form a shape of the seal 1071 on the top and/or bottom plate 1061, 1002.

**[0048]** In one exemplary embodiment, a shape of the seal 1071 is initially formed from the frit paste and interposed between the top plate 1061 and the bottom plate 1002. The seal 1071 can in certain embodiments be pre-cured or pre-sintered to one of the top plate and bottom plate 1061, 1002. Following assembly of the top plate 1061 and the bottom plate 1002 with the seal 1071 interposed therebetween, portions of the seal 1071 are selectively heated such that the frit material forming the seal 1071 at least partially melts. The seal 1071 is then allowed to resolidify to form a secure joint between the top plate 1061 and the bottom plate 1002 to thereby inhibit exposure of the enclosed OLED pixel array 1021 to oxygen or water.

**[0049]** In embodiments, the selective heating of the frit seal is carried out by irradiation of light, such as a laser or directed infrared lamp. As previously noted, the frit material forming the seal 1071 can be combined with one or more additives or filler such as species selected for improved absorption of the irradiated light to facilitate heating and melting of the frit material to form the seal 1071.

**[0050]** In some embodiments, OLED devices 1011 are mass produced. In an embodiment illustrated in Fig. 3E, a plurality of separate OLED arrays 1021 is formed on a common bottom substrate 1101. In the illustrated embodiment, each OLED array 1021 is surrounded by a shaped frit to form the seal 1071. In embodiments, common top substrate (not shown) is placed over the common bottom substrate 1101 and the structures formed thereon such that the OLED arrays 1021 and the shaped frit paste are interposed between the common bottom substrate 1101 and the common top substrate. The OLED arrays 1021 are encapsulated and sealed, such as via the previously described enclosure process for a single OLED display device. The resulting product in-

cludes a plurality of OLED devices kept together by the common bottom and top substrates. Then, the resulting product is cut into a plurality of pieces, each of which constitutes an OLED device 1011 of Fig. 3D. In certain embodiments, the individual OLED devices 1011 then further undergo additional packaging operations to further improve the sealing formed by the frit seal 1071 and the top and bottom substrates 1061, 1002.

**[0051]** Occasionally, the sealing material may not completely prevent moisture or air entering into the enclosed space. Also, there may be cracks in the sealing material and in the interfacial area where the sealing material contacts the substrate for various reasons.

**[0052]** FIG. 1a to FIG. 1f are cross-sectional views showing a method for manufacturing an organic light emitting display according to an embodiment of the present invention. FIG. 2a to FIG. 2f are perspective views showing a method for manufacturing an organic light emitting display according to an embodiment of the present invention. FIG. 1a to FIG. 1f and FIG. 2a to FIG. 2f illustrate an embodiment of the present invention, but the present invention is not limited to the embodiments illustrated in FIG. 1a to FIG. 1f and FIG. 2a to FIG. 2f.

**[0053]** Hereinafter, two display panels among a plurality of display panels that are continuously arranged, are referred to as first display panel 120 and a second display panel 130, respectively. With reference to FIG. 1a and FIG. 2a, at least the first display panel 120 and the second display panel 130 are formed at a first mother substrate 110 in such a way that they are arranged in sequence. The first display panel 120 includes a first pixel region 120a and a first non-pixel region 120b. The second display panel 130 includes a second pixel region 130a and a second non-pixel region 130b. A second mother substrate 160 is positioned at a lower portion of the first mother substrate 110, and covers the first mother substrate 110. A cut line (not shown) is formed at each of the first mother substrate 110 and the second mother substrate 120, which separates respective display panels from each other. For example, a cut line is formed at a boundary between the first pixel region 120b of the first display panel 120 and the second non-pixel region 130b of the second display panel 130.

**[0054]** Referring to FIG. 1b and 2b, in one surface of the second mother substrate 160, a frit 140 is coated at a part corresponding to a peripheral portion of each of the pixel regions 120a and 130a, which seals at least the pixel regions 120a and 130a of the first mother substrate 110. That is, the frit 140 is coated along a peripheral region corresponding to the pixel regions 120a and 130a formed in the first mother substrate 110. In an embodiment, the frit 140 includes a filler (not shown) and an absorbent (not shown). The filler adjusts a thermal expansion coefficient of the frit 140. The absorbent adsorbs laser or infrared ray. The frit 140 is made in a form of a glass powder having an oxide powder. By rapidly reducing a temperature of a heated glass material, the frit 140 is formed in a glass powder pattern. Organic substance

is added to the frit 140 to make a paste in a gel state. Then, the frit 140 is sintered at a predetermined temperature to remove the organic substance. The frit paste in a gel state is cured to form the frit seal 140 in a solid state. In an embodiment, preferably, a temperature of sintering the frit 140 ranges from about 300 °C to about 700°C.

**[0055]** With reference to FIG. 1c and FIG. 2c, after the first mother substrate 110 and the second mother substrate 160 are coalesced to each other, a laser or infrared ray is irradiated to the frit 140, thereby melting the frit 140, and then the frit is cured. Accordingly, the first mother substrate 110 and the second mother substrate 160 are coalesced to each other. The second mother substrate 160 covers the first mother substrate 110, predetermined enclosed space is formed in the device and the organic light emitting pixels are protected from external oxygen or moisture.

**[0056]** Referring to FIG. 1d and FIG. 2d, a cutting process is performed using a cutting machine, and then the first and second mother substrates 110 and 160 coalesced is divided into respective unit display panels. The cutting process is carried out along a cut line (not shown) formed on the first and second mother substrates 110 and 160.

**[0057]** With reference to FIG. 1e and FIG. 2e, the divided unit display panels or unfinished devices are aligned inside an alignment means (not shown). A slot and a partition are provided inside the alignment means to have a structure capable of receiving unit display panels. In an embodiment, the unit display panels are aligned inside the alignment means to be adjacent to each other. A first substrate of a unit display panel which is one of aligned unit display panels and a second substrate in another aligned unit display panel, which is adjacent to the unit display panel, are facing each other and apart from each other. A reinforcing member 150 is formed in each unit display panel, using alignment means to reduce a process time.

**[0058]** Herein, the alignment means is an auxiliary means to easily coat the reinforcing member 150 to be described later, and the invention is not limited to a specific configuration thereof. Moreover, materials which do not have adhesive strength with the reinforcing member 150 may be used in the alignment means in order to easily separate the unit display panels after coating the reinforcing member.

**[0059]** With reference to FIG. 1f and FIG. 2f, the unit display panels 120 and 130 aligned in the alignment means are preferably retained in a slot or a partition provided in the alignment means so that the reinforcing material does not flow on a pixel region of a unit display panel during or after the formation process of the reinforcing member 150.

**[0060]** Next, the reinforcing material is coated at upper portions of the retained unit display panels, and the reinforcing material is formed between the substrates and outside the frit 140 by using a roller 170. In an embodi-

ment, the reinforcing material can be formed using a roll printing method or a simultaneous printing method. In an embodiment, such reinforcing material is made of resin syrup. Acrylate cyanide, acrylate, epoxy, acrylate and urethane acrylate may be used as the reinforcing member 150. The acrylate cyanide is a material that is naturally cured. The acrylate is a material that is thermally cured at a temperature less than about 80 °C. The epoxy acrylate and urethane acrylate are a material that is cured by ultra-violet ray. In an embodiment, after separating the unit display panels from the alignment means, ultra-violet curing, natural curing, or thermal process for the reinforcing material is performed to form reinforcing member 150.

**[0061]** As apparent from the above description, in accordance with the present invention, a reinforcing member is further formed outside the frit adhering first and second substrates to each other. This may prevent an organic light emitting display from easily being broken or damaged due to impact, and improve reliability of the device. Moreover, this may perfectly protect organic light emitting pixels from the ambient environment. Also, after aligning or arranging a plurality of unit display panels, reinforcing members are simultaneously formed. Accordingly, this method can reduce a process time as compared with a method of forming reinforcing members one by one of respective unit display panels, and therefore, the present invention extremely enhances mass productivity of an organic light emitting display.

**[0062]** Although a few embodiments of the present invention have been shown and described, it would be appreciated by those skilled in the art that changes might be made in this embodiment without departing from the principles of the invention, the scope of which is defined in the claims.

## Claims

1. A method for making an organic light emitting display device, the method comprising:

providing a first (120) and a second device (130), each device (120, 130) comprising:

a first substrate (110) comprising front and back surfaces and a first side surface,  
a second substrate (160) comprising front and back surfaces and a first side surface and opposing the first substrate (110),  
an array of organic light emitting pixels interposed between the first and the second substrate (110, 160),  
a frit seal (140) interposed between the first substrate (110) and the second substrate (160) while surrounding the array, wherein the frit seal (140), the first substrate (110) and the second substrate (160) together de-

- fine an enclosed space in which the array is located, the frit seal (140) comprising a first side surface, and  
a first side comprising the first side surfaces of the first substrate (110), the second substrate (160) and the frit seal (140);  
arranging the first and the second device (120, 130) such that the first substrate (110) of the first device opposes the first or second substrate (110, 160) of the second device (120) and that the first sides of the first and second device (120, 130) face substantially the same direction;  
applying a material onto the first sides of the first and the second device (120, 130), the material being configured to form a reinforcing structure (150) when cured; and  
curing the material so as to form a reinforcing structure (150) comprising a first portion contacting the first side of the first device (120) and a second portion contacting the first side of the second device (130).
2. The Method according to Claim 1, wherein arranging comprises:
    - providing a holder configured to hold the first and second device (120, 130); and  
holding the first and second device (120, 130) such that the first substrate (110) of the first device (120) opposing the first or second substrate (110, 160) of the second device (130) and that the first sides of the first and second device (120, 130) face substantially the same direction.
  3. The Method according to Claim 1 or 2, wherein applying the material while holding the first and second device (120, 130) together.
  4. The Method according to one of the proceeding claims 1 and 3,  
wherein applying the material comprises causing a medium retaining the material to contact the first sides of the first and second device (120, 130).
  5. The Method according to Claim 4, wherein applying comprises sliding the medium on the first sides of the first and second device (120, 130).
  6. The Method according to Claim 4, wherein the medium comprise a brush.
  7. The Method according to Claim 4, wherein the medium is arranged with a roll comprising a rotatable cylinder, and wherein applying comprises rolling the roll over the first side of the first and second device (120, 130) while contacting at least part of the first side.
  8. The Method according to one of the proceeding claim 1, wherein the first substrate (110), the second substrate (160) and the frit seal (140) in combination form a gap space outside the enclosed space in each of the first and second device (120, 130), and wherein at least part of the material enters into the gap space.
  9. The Method according to Claim 8, wherein applying the material comprises causing the material to enter into the gap space.
  10. The Method according to Claim 9, wherein at least part of the material entering into the gap space spontaneously moves toward the frit seal (140).
  11. The method of Claim 8, wherein the gap space has a depth from the first side surface of the first substrate (120) to the first side surface of the frit seal (140), and wherein the depth is from 0.3 mm to 0.7 mm.
  12. The Method according to Claim 8, wherein the distance between the first and second substrate (110, 160) in the gap space is from 2  $\mu\text{m}$  to 30  $\mu\text{m}$ .
  13. The Method according to one of the proceeding claims, wherein applying the material comprises causing the material to contact at least part of the first side of the first device (120) and at least part of the first side of the second device (130).
  14. The Method according to one of the proceeding claims, wherein applying the material comprises causing the material to contact the first side surface of the frit seal (140) in each of the first and second device (120, 130).
  15. The Method according to one of the proceeding claims, wherein the material has a viscosity less than 200 cp.
  16. The Method according to one of the proceeding claims, wherein arranging comprises placing an insert between the first substrate (110) of the first device (120) and the first or second substrate (110, 160) of the second device (130)..
  17. The Method according to one of the proceeding claims, wherein arranging comprises contacting the first substrate (110) of the first device (120) with the first or second substrate (110, 160) of the second device (130).
  18. The Method according to one of the proceeding claims, wherein the first substrate (110) of the first device (120) is arranged substantially parallel to the first or second substrate (110, 160) of the second device (130).

19. The Method according to one of the proceeding claims, wherein the first side surface of the frit seal (140) is substantially parallel to the first side surface of the first substrate (110).
20. The Method according to one of the proceeding claims 1, wherein the first portion contacts the frit seal (140) of the first device (120).
21. The Method according to one of the proceeding claims, wherein the first and second portion are integrated after curing.
22. The Method according to one of the proceeding claims, further comprising separating the first portion from the second portion.
23. The Method according to one of the proceeding claims, wherein each of the first and second devices (120, 130) comprises a second side comprising a second side surface of the first substrate (110), the second substrate (160) and the frit seal (140), wherein the method further comprises applying the material onto the second sides of the first and second device (120, 130).
24. The Method according to one of the proceeding claims, further comprising providing at least one additional device comprising:
- a first substrate (110) comprising front and back surfaces and a first side surface
  - a second substrate (160) comprising front and back surfaces and a first side surface and opposing the first substrate (110),
  - an array of organic light emitting pixels interposed between the first and second substrate (110, 160),
  - a frit seal (140) interposed between the first substrate and the second substrate (110, 160) while surrounding the array, wherein the frit seal (140), the first substrate and the second substrate (110, 160) together define an enclosed space in which the array is located, the frit seal (140) comprising a first side surface, and
  - a first side comprising the first side surface of the first substrate (110), the second substrate (160) and the frit seal (140);
  - wherein arranging further arranges the at least one additional device together with the first and second devices (120, 130);
  - wherein applying further applies the material on the at least one additional device; and
  - wherein curing forms at least one additional structure, each of which contacts the first side of each of the at least one additional device.
25. The Method according to one of the proceeding

claims, wherein the frit seal (140) comprises one or more materials selected from the group consisting of magnesium oxide (MgO), calcium oxide (CaO), barium oxide (BaO), lithium oxide (Li<sub>2</sub>O), sodium oxide (Na<sub>2</sub>O), potassium oxide (K<sub>2</sub>O), boron oxide (B<sub>2</sub>O<sub>3</sub>), vanadium oxide (V<sub>2</sub>O<sub>5</sub>), zinc oxide (ZnO), tellurium oxide (TeO<sub>2</sub>), aluminium oxide (Al<sub>2</sub>O<sub>3</sub>), silicon dioxide (SiO<sub>2</sub>), lead oxide (PbO), tin oxide (SnO), phosphorous oxide (P<sub>2</sub>O<sub>5</sub>), ruthenium oxide (Ru<sub>2</sub>O), rubidium oxide (Rb<sub>2</sub>O), rhodium oxide (Rh<sub>2</sub>O), ferrite oxide (Fe<sub>2</sub>O<sub>3</sub>), copper oxide (CuO), titanium oxide (TiO<sub>2</sub>), tungsten oxide (WO<sub>3</sub>), bismuth oxide (Bi<sub>2</sub>O<sub>3</sub>), antimony oxide (Sb<sub>2</sub>O<sub>3</sub>), lead-borate glass, tin-phosphate glass, vanadate glass, and borosilicate.

### Patentansprüche

1. Ein Verfahren zur Herstellung einer organischen lichtemittierenden Anzeigevorrichtung, wobei das Verfahren Folgendes umfasst:

Bereitstellen einer ersten (120) und einer zweiten Vorrichtung (130), wobei jede Vorrichtung (120, 130) Folgendes umfasst:

ein erstes Substrat (110), das vordere und hintere Oberflächen sowie eine erste seitliche Oberfläche umfasst,

ein zweites Substrat (160), das vordere und hintere Oberflächen sowie eine erste seitliche Oberfläche umfasst und dem ersten Substrat (110) gegenüberliegt,

ein Array von zwischen dem ersten und dem zweiten Substrat (110, 160) eingefügten organischen lichtemittierenden Pixeln,

eine Frittendichtung (140), die zwischen dem ersten Substrat (110) und dem zweiten Substrat (160) eingefügt ist und dabei das Array umgibt, wobei die Frittendichtung (140), das erste Substrat (110) und das zweite Substrat (160) zusammen einen umschlossenen Raum definieren, in dem das Array angeordnet ist, wobei die Frittendichtung (140) eine erste seitliche Oberfläche umfasst, und

eine erste Seite, die die ersten seitlichen Oberflächen des ersten Substrats (110), des zweiten Substrats (160) und der Frittendichtung (140) umfasst;

Anordnen der ersten und der zweiten Vorrichtung (120, 130), so dass das erste Substrat (110) der ersten Vorrichtung dem ersten oder zweiten Substrat (110, 160) der zweiten Vorrichtung (120) gegenüberliegt und dass die ersten Seiten der ersten und zweiten Vorrichtung (120, 130) im Wesent-

- lichen in dieselbe Richtung zeigen;  
Auftragen eines Materials auf die ersten  
Seiten der ersten und zweiten Vorrichtung  
(120, 130), wobei das Material dazu ausge-  
legt ist, eine verstärkende Struktur (150) zu  
bilden, wenn es ausgehärtet ist; und  
Aushärten des Materials, um eine verstär-  
kende Struktur (150) zu bilden, die einen  
ersten Teil, der die erste Seite der ersten  
Vorrichtung (120) berührt, sowie einen  
zweiten Teil, der die erste Seite der zweiten  
Vorrichtung (130) berührt, umfasst.
2. Das Verfahren gemäß Anspruch 1, wobei das An-  
ordnen Folgendes umfasst:
- Bereitstellen eines Halters, der dazu ausgelegt  
ist, die erste und zweite Vorrichtung (120, 130)  
zu halten; und  
Halten der ersten und zweiten Vorrichtung (120,  
130), so dass das erste Substrat (110) der er-  
sten Vorrichtung (120) dem ersten oder zweiten  
Substrat (110, 160) der zweiten Vorrichtung  
(130) gegenüberliegt und dass die ersten Seiten  
der ersten und zweiten Vorrichtung (120, 130)  
im Wesentlichen in dieselbe Richtung zeigen.
3. Das Verfahren gemäß Anspruch 1 oder 2, umfas-  
send Auftragen des Materials während die ersten  
und zweite Vorrichtung (120, 130) zusammengehal-  
ten werden.
4. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche 1 und 3, wobei das Auftragen des Mate-  
rials umfasst, zu verursachen, dass ein Medium, das  
das Material hält, die ersten Seiten der ersten und  
zweiten Vorrichtung (120, 130) berührt.
5. Das Verfahren gemäß Anspruch 4, wobei das Auf-  
bringen Schieben des Mediums auf den ersten Sei-  
ten der ersten und zweiten Vorrichtung (120, 130)  
umfasst.
6. Das Verfahren gemäß Anspruch 4, wobei das Me-  
dium eine Bürste umfasst.
7. Das Verfahren gemäß Anspruch 4, wobei das Me-  
dium mit einer einen rotierbaren Zylinder umfassen-  
den Walze angeordnet wird und wobei das Auftragen  
Rollen der Walze über die erste Seite der ersten und  
zweiten Vorrichtung (120, 130) umfasst, wobei sie  
zumindest einen Teil der ersten Seite berührt.
8. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche 1, wobei das erste Substrat (110), das  
zweite Substrat (160) und die Frittendichtung (140)  
in Kombination einen Zwischenraum außerhalb des  
umschlossenen Raumes in jeder der ersten und
- zweiten Vorrichtung (120, 130) bilden und wobei zu-  
mindest ein Teil des Materials in den Zwischenraum  
eindringt.
9. Das Verfahren gemäß Anspruch 8, wobei das Auf-  
tragen des Materials umfasst, Eindringen des Mate-  
rials in den Zwischenraum zu verursachen.
10. Das Verfahren gemäß Anspruch 9, wobei zumindest  
ein Teil des Materials, das in den Zwischenraum ein-  
dringt, sich spontan in Richtung der Frittendichtung  
(140) bewegt.
11. Das Verfahren nach Anspruch 8, wobei der Zwi-  
schenraum eine Tiefe von der ersten seitlichen  
Oberfläche des ersten Substrats (120) zu der ersten  
seitlichen Oberfläche der Frittendichtung (140) auf-  
weist und wobei die Tiefe zwischen 0,3 mm und 0,7  
mm liegt.
12. Das Verfahren gemäß Anspruch 8, wobei der Ab-  
stand zwischen dem ersten und zweiten Substrat  
(110, 160) in dem Zwischenraum zwischen 2  $\mu\text{m}$   
und 30  $\mu\text{m}$  liegt.
13. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das Auftragen des Materials um-  
fasst, zu verursachen, dass das Material zumindest  
einen Teil der ersten Seite der ersten Vorrichtung  
(120) und zumindest einen Teil der ersten Seite der  
zweiten Vorrichtung (130) berührt.
14. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das Auftragen des Materials um-  
fasst, zu verursachen, dass das Material in jeder der  
ersten und zweiten Vorrichtung (120, 130) die erste  
seitliche Oberfläche der Frittendichtung (140) be-  
rührt.
15. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das Material eine Viskosität von  
weniger als 200 cp aufweist.
16. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das Anordnen Platzieren eines  
Einsatzes zwischen dem ersten Substrat (110) der  
ersten Vorrichtung (120) und dem ersten oder zwei-  
ten Substrat (110, 160) der zweiten Vorrichtung  
(130) umfasst.
17. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das Anordnen umfasst, das erste  
Substrat (110) der ersten Vorrichtung (120) mit dem  
ersten oder zweiten Substrat (110, 160) der zweiten  
Vorrichtung (130) in Berührung zu bringen.
18. Das Verfahren gemäß einem der vorhergehenden  
Ansprüche, wobei das erste Substrat (110) der er-

sten Vorrichtung (120) im Wesentlichen parallel zu dem ersten oder zweiten Substrat (110, 160) der zweiten Vorrichtung (130) angeordnet ist.

19. Das Verfahren gemäß einem der vorhergehenden Ansprüche, wobei die erste seitliche Oberfläche der Frittendichtung (140) im Wesentlichen parallel zu der ersten seitlichen Oberfläche des ersten Substrats (110) liegt. 5
20. Das Verfahren gemäß einem der vorhergehenden Ansprüche 1, wobei der erste Teil die Frittendichtung (140) der ersten Vorrichtung (120) berührt. 10
21. Das Verfahren gemäß einem der vorhergehenden Ansprüche, wobei der erste und der zweite Teil nach dem Aushärten integriert sind. 15
22. Das Verfahren gemäß einem der vorhergehenden Ansprüche, ferner umfassend Trennen des ersten Teils von dem zweiten Teil. 20
23. Das Verfahren gemäß einem der vorhergehenden Ansprüche, wobei jede der ersten und zweiten Vorrichtungen (120, 130) eine zweite Seite umfasst, die eine zweite seitliche Oberfläche des ersten Substrats (110), des zweiten Substrats (160) und der Frittendichtung (140) umfasst, wobei das Verfahren ferner Auftragen des Materials auf die zweiten Seiten der ersten und zweiten Vorrichtung (120, 130) umfasst. 25 30
24. Das Verfahren gemäß einem der vorhergehenden Ansprüche, ferner umfassend Bereitstellen mindestens einer zusätzlichen Vorrichtung, die Folgendes umfasst: 35  
ein erstes Substrat (110), das vordere und hintere Oberflächen sowie eine erste seitliche Oberfläche umfasst, 40  
ein zweites Substrat (160), das vordere und hintere Oberflächen sowie eine erste seitliche Oberfläche umfasst und dem ersten Substrat (110) gegenüberliegt,  
ein Array von zwischen dem ersten und zweiten Substrat (110, 160) eingefügten organischen lichtemittierenden Pixeln, 45  
eine Frittendichtung (140), die zwischen dem ersten Substrat und dem zweiten Substrat (110, 160) eingefügt ist und dabei das Array umgibt, 50  
wobei die Frittendichtung (140), das erste Substrat und das zweite Substrat (110, 160) zusammen einen umschlossenen Raum definieren, in dem das Array angeordnet ist, wobei die Frittendichtung (140) eine erste seitliche Oberfläche umfasst, und 55  
eine erste Seite, die die erste seitliche Oberfläche des ersten Substrats (110), des zweiten

Substrats (160) und der Frittendichtung (140) umfasst;

wobei das Anordnen ferner die mindestens eine zusätzliche Vorrichtung zusammen mit den ersten und zweiten Vorrichtungen (120, 130) anordnet;

wobei das Auftragen ferner das Material auf der mindestens einen zusätzlichen Vorrichtung aufträgt; und

wobei das Aushärten mindestens eine zusätzliche Struktur bildet, deren jede die erste Seite jeder der mindestens einen zusätzlichen Vorrichtung berührt.

25. Das Verfahren gemäß einem der vorhergehenden Ansprüche, wobei die Frittendichtung (140) ein oder mehrere aus der aus Magnesiumoxid (MgO), Calciumoxid (CaO), Bariumoxid (BaO), Lithiumoxid (Li<sub>2</sub>O), Natriumoxid (Na<sub>2</sub>O), Kaliumoxid (K<sub>2</sub>O), Bortrioxid (B<sub>2</sub>O<sub>3</sub>), Vanadiumoxid (V<sub>2</sub>O<sub>5</sub>), Zinkoxid (ZnO), Tellurtrioxid (TeO<sub>3</sub>), Aluminiumoxid (Al<sub>2</sub>O<sub>3</sub>), Siliciumdioxid (SiO<sub>2</sub>), Bleioxid (PbO), Zinnoxid (SnO), Phosphorpentoxid (P<sub>2</sub>O<sub>5</sub>), Rutheniumoxid (Ru<sub>2</sub>O), Rubidiumoxid (Rb<sub>2</sub>O), Rhodiumoxid (Rh<sub>2</sub>O), Ferritoxid (Fe<sub>2</sub>O<sub>3</sub>), Kupferoxid (CuO), Titanoxid (TiO<sub>2</sub>), Wolframoxid (WO<sub>3</sub>), Bismutoxid (Bi<sub>2</sub>O<sub>3</sub>), Antimonoxid (Sb<sub>2</sub>O<sub>3</sub>), Bleiboratglas, Zinnphosphatglas, Vanadatglas, und Borosilikat bestehenden Gruppe ausgewählte Materialien umfasst.

## Revendications

1. Procédé pour réaliser un dispositif d'affichage électroluminescent organique, le procédé comprenant :

la disposition d'un premier (120) et d'un deuxième (130) dispositif, chaque dispositif (120, 130) comprenant :

un premier substrat (110) comprenant des surfaces avant et arrière et une première surface latérale,

un deuxième substrat (160) comprenant des surfaces avant et arrière et une première surface latérale, et opposé au premier substrat (110),

un groupement de pixels électroluminescents organiques interposés entre le premier et le deuxième substrat (110, 160),

un joint d'étanchéité fritté (140) interposé entre le premier substrat (110) et le deuxième substrat (160) tout en entourant le groupement, le joint d'étanchéité fritté (140), le premier substrat (110) et le deuxième substrat (160) définissant ensemble un espace clos dans lequel est situé le groupement, le joint d'étanchéité fritté (140) comprenant

- une première surface latérale, et un premier côté comprenant les premières surfaces latérales du premier substrat (110), du deuxième substrat (160) et du joint d'étanchéité fritté (140) ;  
la disposition du premier et du deuxième dispositif (120, 130) de telle sorte que le premier substrat (110) du premier dispositif soit opposé au premier ou au deuxième substrat (110, 160) du deuxième dispositif (120), et que les premiers côtés des premier et deuxième dispositifs (120, 130) soient sensiblement dirigés dans la même direction ; l'application d'un matériau sur les premiers côtés du premier et du deuxième dispositif (120, 130), le matériau étant configuré de façon à former une structure de renfort (150) lorsqu'il est durci ; et le durcissement du matériau de façon à former une structure de renfort (150) comprenant une première partie venant en contact avec le premier côté du premier dispositif (120) et une deuxième partie venant en contact avec le premier côté du deuxième dispositif (130).
2. Procédé selon la revendication 1, dans lequel l'agencement comprend :
- la disposition d'un support configuré de façon à supporter les premier et deuxième dispositifs (120, 130) ; et le support des premier et deuxième dispositifs (120, 130) de telle sorte que le premier substrat (110) du premier dispositif (120) soit opposé au premier ou au deuxième substrat (110, 160) du deuxième dispositif (130) et que les premiers côtés des premier et deuxième dispositifs (120, 130) soient sensiblement dirigés dans la même direction.
3. Procédé selon la revendication 1 ou 2, dans lequel l'application du matériau se fait tout en maintenant les premier et deuxième dispositifs (120, 130) réunis.
4. Procédé selon l'une des revendications 1 et 3 qui précèdent, dans lequel l'application du matériau comprend le fait de faire retenir le matériau par un milieu de façon à ce qu'il vienne en contact avec les premiers côtés des premier et deuxième dispositifs (120, 130).
5. Procédé selon la revendication 4, dans lequel l'application comprend le fait de faire coulisser le milieu sur les premiers côtés des premier et deuxième dispositifs (120, 130).
6. Procédé selon la revendication 4, dans lequel le milieu comprend une brosse.
7. Procédé selon la revendication 4, dans lequel le milieu est agencé avec un rouleau comprenant un cylindre rotatif, et dans lequel l'application comprend le fait de faire rouler le rouleau sur le premier côté des premier et deuxième dispositifs (120, 130) tout en venant en contact avec au moins une partie du premier côté.
8. Procédé selon l'une de la revendication 1 qui précède, dans lequel le premier substrat (110), le deuxième substrat (160) et le joint d'étanchéité fritté (140), en combinaison, forment un espace d'espacement à l'extérieur de l'espace clos dans chacun des premier et deuxième dispositifs (120, 130), et dans lequel au moins une partie du matériau entre dans l'espace d'espacement.
9. Procédé selon la revendication 8, dans lequel l'application du matériau comprend le fait de faire entrer le matériau dans l'espace d'espacement.
10. Procédé selon la revendication 9, dans lequel au moins une partie du matériau entrant dans l'espace d'espacement se déplace spontanément vers le joint d'étanchéité fritté (140).
11. Procédé selon la revendication 8, dans lequel l'espace d'espacement a une profondeur de la première surface latérale du premier substrat (120) à la première surface latérale du joint d'étanchéité fritté (140), et dans lequel la profondeur est comprise entre 0,3 mm et 0,7 mm.
12. Procédé selon la revendication 8, dans lequel la distance entre les premier et deuxième substrats (110, 160) dans l'espace d'espacement est comprise entre 2  $\mu\text{m}$  et 30  $\mu\text{m}$ .
13. Procédé selon l'une des revendications précédentes, dans lequel l'application du matériau comprend le fait d'amener le matériau à venir en contact avec au moins une partie du premier côté du premier dispositif (120) et au moins une partie du premier côté du deuxième dispositif (130).
14. Procédé selon l'une des revendications précédentes, dans lequel l'application du matériau comprend le fait d'amener le matériau à venir en contact avec la première surface latérale du joint d'étanchéité fritté (140) dans chacun des premier et deuxième dispositifs (120, 130).
15. Procédé selon l'une des revendications précédentes, dans lequel le matériau a une viscosité inférieure à 200 cp.

16. Procédé selon l'une des revendications précédentes, dans lequel l'agencement comprend la disposition d'un insert entre le premier substrat (110) du premier dispositif (120) et le premier ou le deuxième substrat (110, 160) du deuxième dispositif (130). 5
17. Procédé selon l'une des revendications précédentes, dans lequel l'agencement comprend la mise en contact du premier substrat (110) du premier dispositif (120) avec le premier ou le deuxième substrat (110, 160) du deuxième dispositif (130). 10
18. Procédé selon l'une des revendications précédentes, dans lequel le premier substrat (110) du premier dispositif (120) est disposé sensiblement parallèlement au premier ou au deuxième substrat (110, 160) du deuxième dispositif (130). 15
19. Procédé selon l'une des revendications précédentes, dans lequel la première surface latérale du joint d'étanchéité fritté (140) est sensiblement parallèle à la première surface latérale du premier substrat (110). 20
20. Procédé selon l'une de la revendication 1 qui précède, dans lequel la première partie vient en contact avec le joint d'étanchéité fritté (140) du premier dispositif (120). 25
21. Procédé selon l'une des revendications précédentes, dans lequel les première et deuxième parties sont intégrées après le durcissement. 30
22. Procédé selon l'une des revendications précédentes, comprenant de plus la séparation de la première partie et de la deuxième partie. 35
23. Procédé selon l'une des revendications précédentes, dans lequel chacun des premier et deuxième dispositifs (120, 130) comprend un deuxième côté comprenant une deuxième surface latérale du premier substrat (110), du deuxième substrat (160) et du joint d'étanchéité fritté (140), le procédé comprenant de plus l'application du matériau sur les deuxièmes côtés des premier et deuxième dispositifs (120, 130). 40
24. Procédé selon l'une des revendications précédentes, comprenant de plus la disposition d'au moins un dispositif additionnel comprenant : 45
- un premier substrat (110) comprenant des surfaces avant et arrière et une première surface latérale, 50
- un deuxième substrat (160) comprenant des surfaces avant et arrière et une première surface latérale, et opposé au premier substrat (110),

un groupement de pixels électroluminescents organiques interposés entre le premier et le deuxième substrat (110, 160),  
 un joint d'étanchéité fritté (140) interposé entre le premier substrat et le deuxième substrat (110, 160) tout en entourant le groupement, le joint d'étanchéité fritté (140), le premier substrat et le deuxième substrat (110, 160) définissant ensemble un espace clos dans lequel est situé le groupement, le joint d'étanchéité fritté (140) comprenant une première surface latérale, et un premier côté comprenant la première surface latérale du premier substrat (110), du deuxième substrat (160) et du joint d'étanchéité fritté (140) ;  
 dans lequel l'agencement dispose de plus le dispositif additionnel au nombre d'au moins un avec les premier et deuxième dispositifs (120, 130) ;  
 dans lequel l'application applique de plus le matériau sur le dispositif additionnel au nombre d'au moins un ; et  
 dans lequel le durcissement forme au moins une structure additionnelle, chacune d'entre elles venant en contact avec le premier côté de chacun des dispositifs additionnels au nombre d'au moins un.

25. Procédé selon l'une des revendications précédentes, dans lequel le joint d'étanchéité fritté (140) comprend un ou plusieurs matériaux sélectionnés parmi le groupe comprenant l'oxyde de magnésium (MgO), l'oxyde de calcium (CaO), l'oxyde de baryum (BaO), l'oxyde de lithium (Li<sub>2</sub>O), l'oxyde de sodium (Na<sub>2</sub>O), l'oxyde de potassium (K<sub>2</sub>O), l'oxyde de bore (B<sub>2</sub>O<sub>3</sub>), l'oxyde de vanadium (V<sub>2</sub>O<sub>5</sub>), l'oxyde de zinc (ZnO), l'oxyde de tellure (TeO<sub>2</sub>), l'oxyde d'aluminium (Al<sub>2</sub>O<sub>3</sub>), le dioxyde de silicium (SiO<sub>2</sub>), l'oxyde de plomb (PbO), l'oxyde d'étain (SnO), l'oxyde phosphoreux (P<sub>2</sub>O<sub>5</sub>), l'oxyde de ruthénium (Ru<sub>2</sub>O), l'oxyde de rubidium (Rb<sub>2</sub>O), l'oxyde de rhodium (Rh<sub>2</sub>O), l'oxyde ferreux (Fe<sub>2</sub>O<sub>3</sub>), l'oxyde de cuivre (CuO), l'oxyde de titane (TiO<sub>2</sub>), l'oxyde de tungstène (WO<sub>3</sub>), l'oxyde de bismuth (Bi<sub>2</sub>O<sub>3</sub>), l'oxyde d'antimoine (Sb<sub>2</sub>O<sub>3</sub>), le verre de borate de plomb, le verre de phosphate d'étain, le verre de vanadate, et le borosilicate.

FIG. 1A

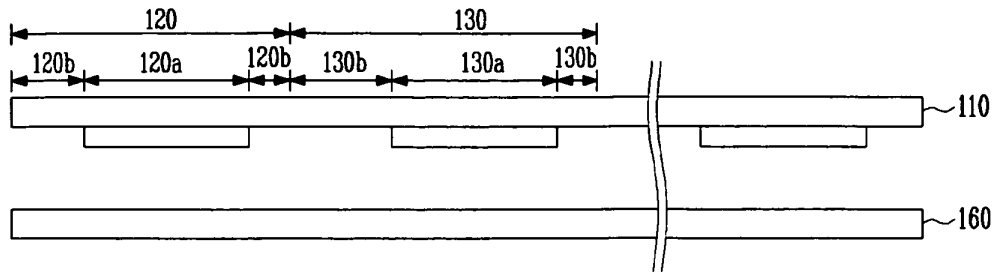


FIG. 1B

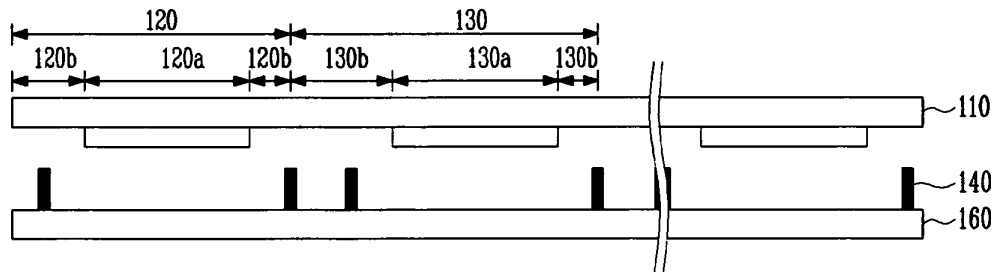


FIG. 1C

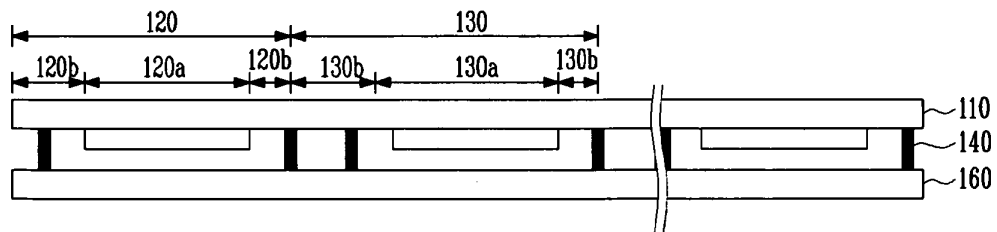


FIG. 1D

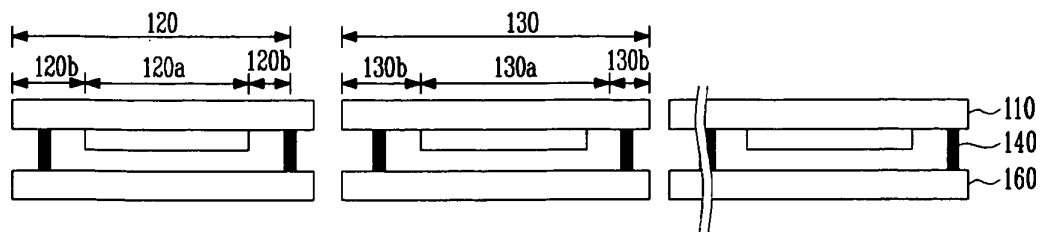


FIG. 1E

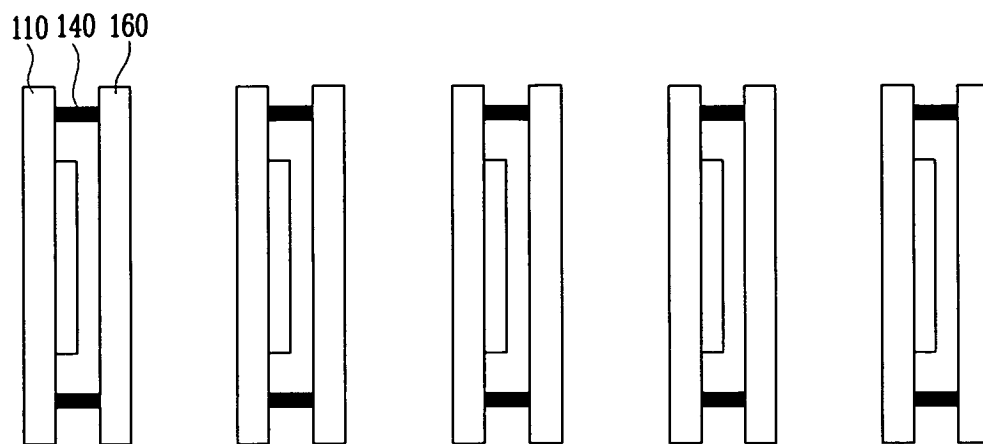


FIG. 1F

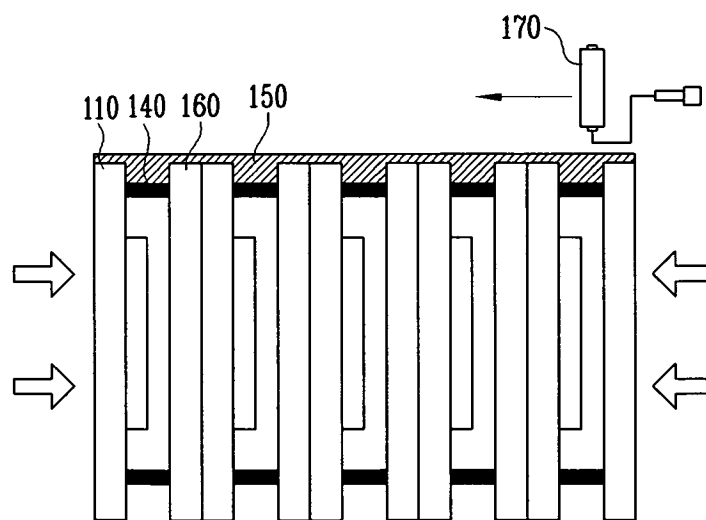


FIG. 2A

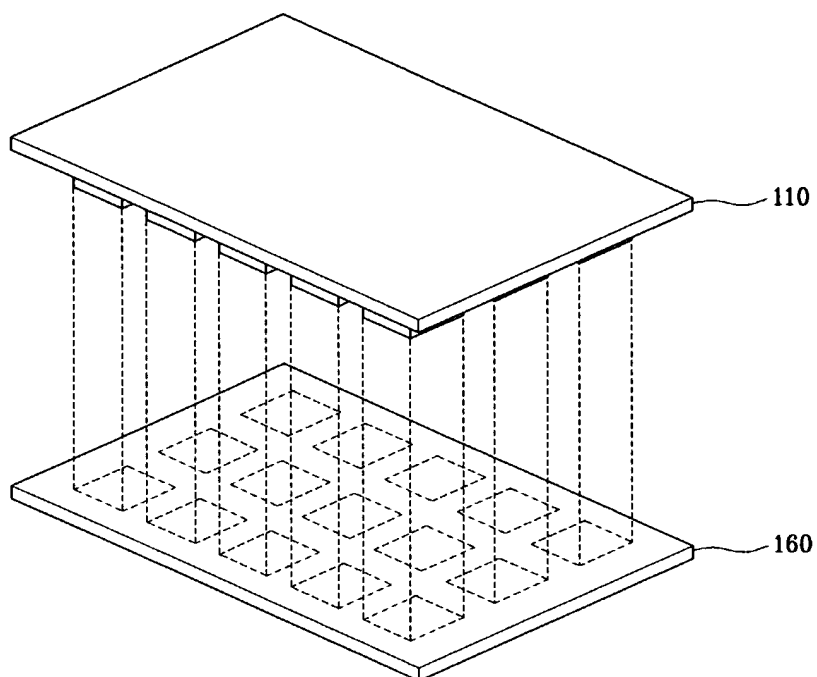


FIG. 2B

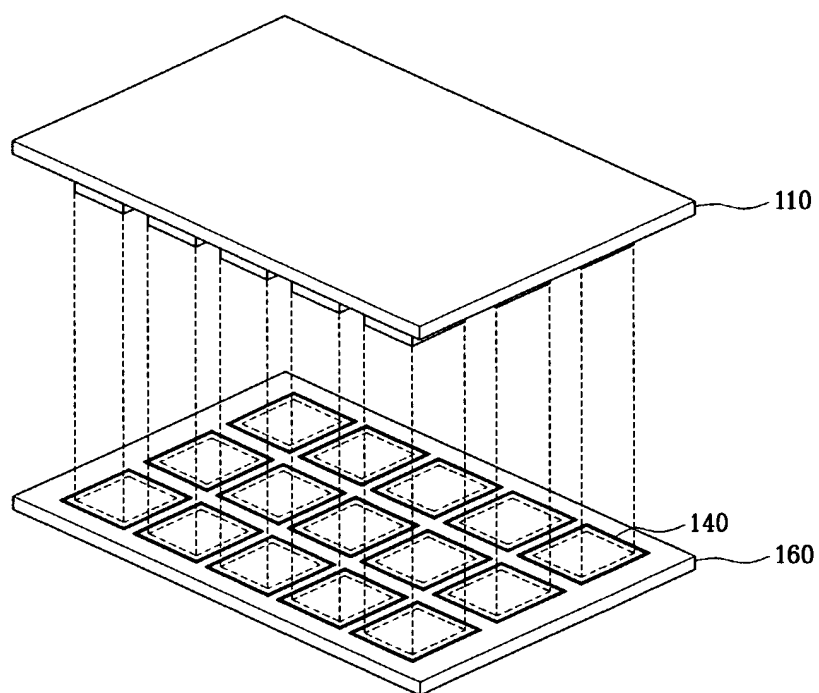


FIG. 2C

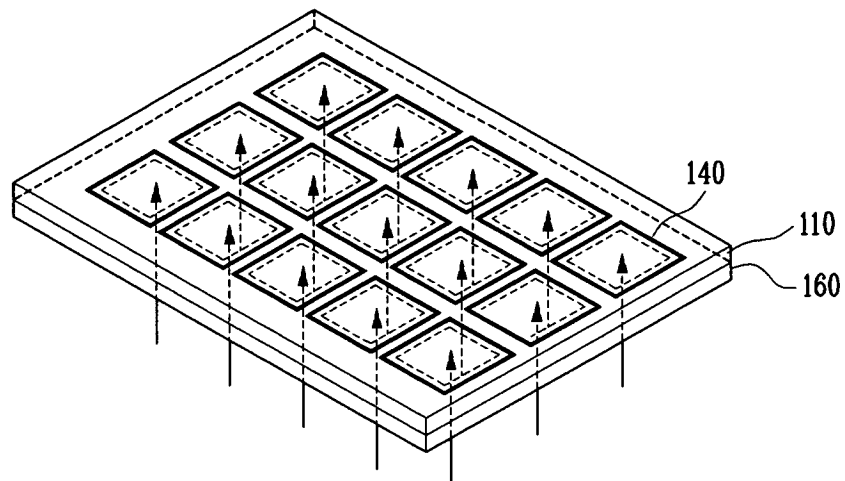


FIG. 2D

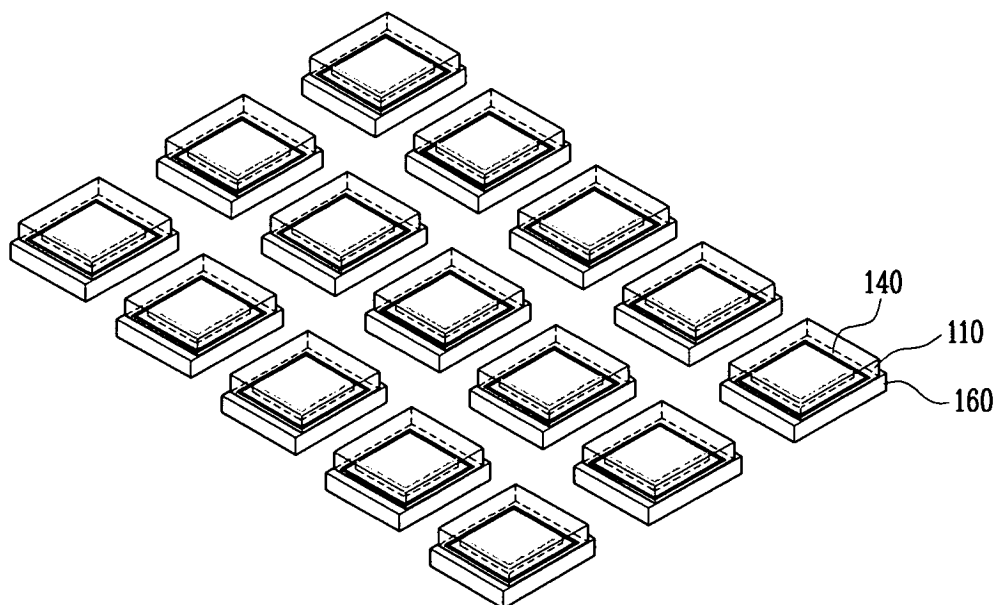


FIG. 2E

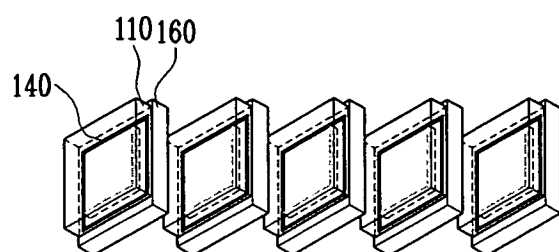


FIG. 2F

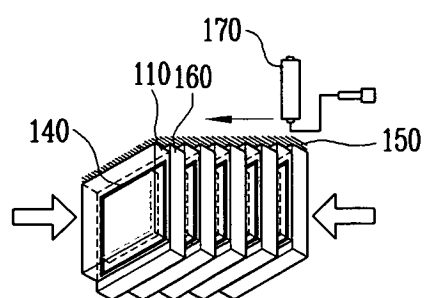


FIG. 3A

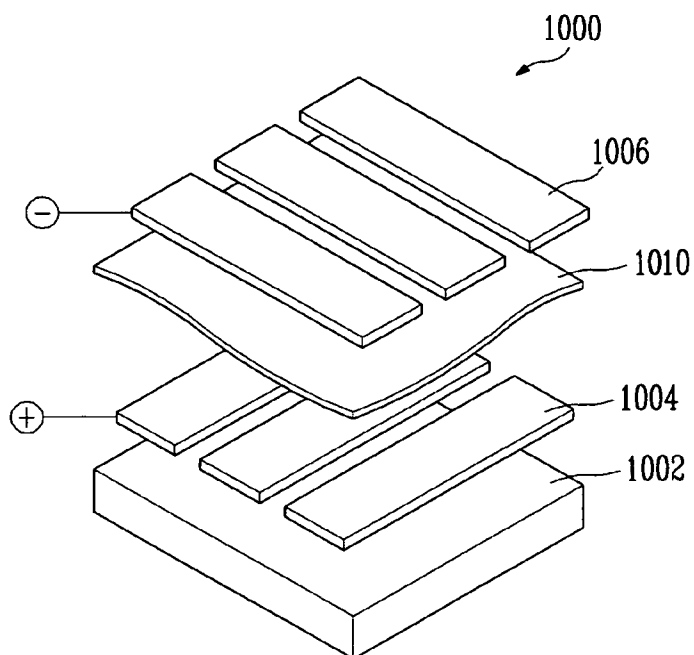


FIG. 3B

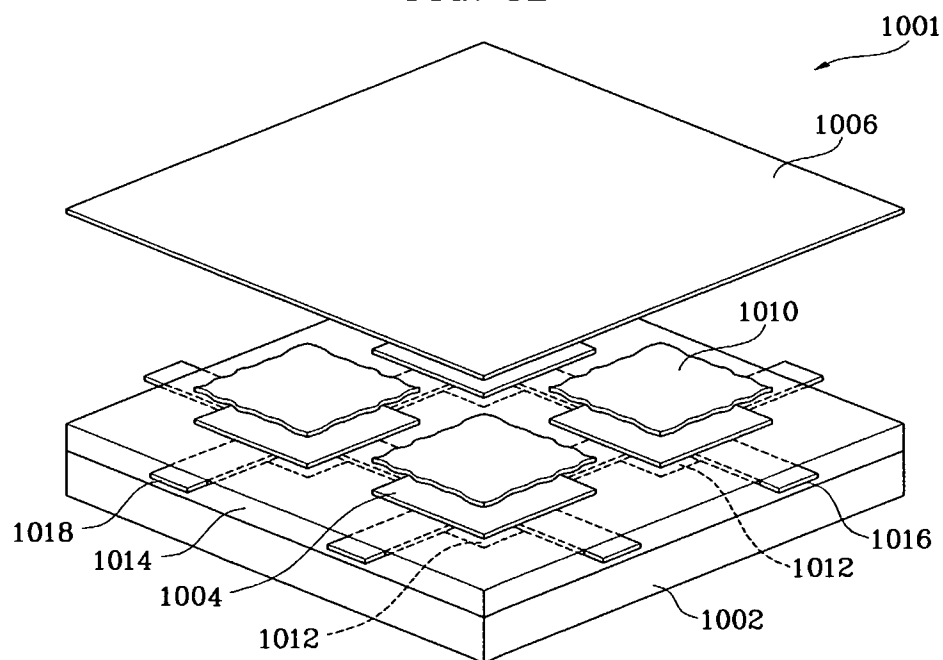


FIG. 3C

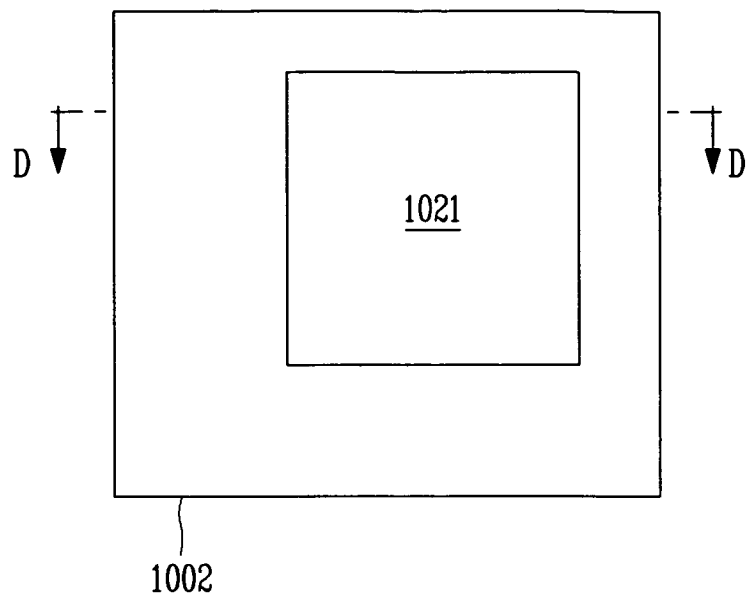


FIG. 3D

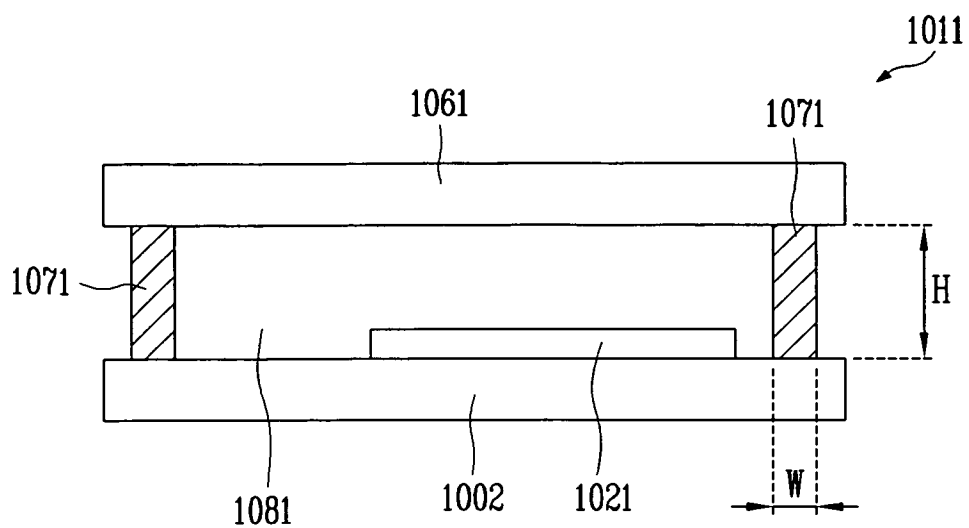
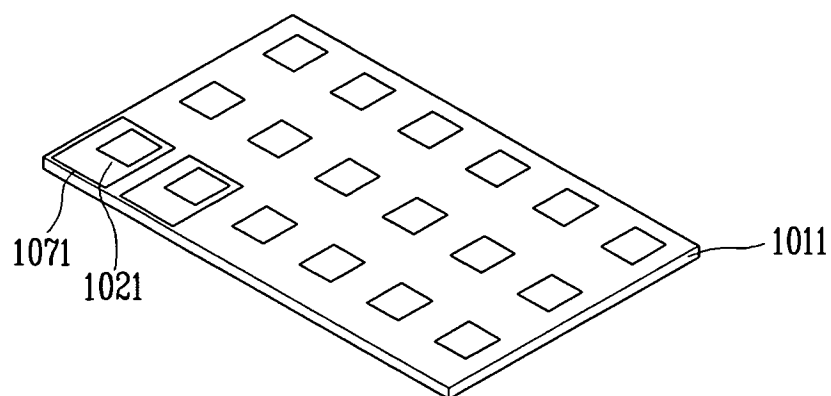


FIG. 3E



**REFERENCES CITED IN THE DESCRIPTION**

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**Patent documents cited in the description**

- US 20040069017 A [0005]
- US 6998776 B2 [0006]

|                |                                                                                                                  |         |            |
|----------------|------------------------------------------------------------------------------------------------------------------|---------|------------|
| 专利名称(译)        | 用于封装具有玻璃料密封件和增强结构的有机发光显示器的方法                                                                                     |         |            |
| 公开(公告)号        | <a href="#">EP1821353B1</a>                                                                                      | 公开(公告)日 | 2009-08-26 |
| 申请号            | EP2007101295                                                                                                     | 申请日     | 2007-01-29 |
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| [标]发明人         | LEE JAE SUN                                                                                                      |         |            |
| 发明人            | LEE, JAE SUN                                                                                                     |         |            |
| IPC分类号         | H01L51/52                                                                                                        |         |            |
| CPC分类号         | H01L51/5246 H01L24/97 H01L25/046 H01L51/524 H01L2251/566 H01L2924/0002 H01L2924/12042 H01L2924/12044 H01L2924/00 |         |            |
| 代理机构(译)        | hengelhaupt , Jürgen                                                                                             |         |            |
| 优先权            | 1020060016856 2006-02-21 KR                                                                                      |         |            |
| 其他公开文献         | EP1821353A1                                                                                                      |         |            |
| 外部链接           | <a href="#">Espacenet</a>                                                                                        |         |            |

#### 摘要(译)

公开了一种通过在单位显示面板的非像素区域上滚动保持可固化材料的辊而在第一基板和第二基板之间封装有机发光显示器的方法。有机发光像素阵列形成在第一母基板的多个像素区域处。在与第一母基板的非像素区域对应的第二母基板的位置处形成玻璃料。母基板彼此聚结并由玻璃料密封。将第一和第二母基板切割成单元显示板。单元显示面板对齐。可固化材料涂覆在单元显示板的一侧并固化以形成加强构件。

